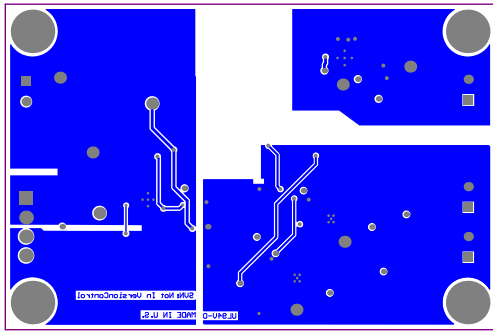
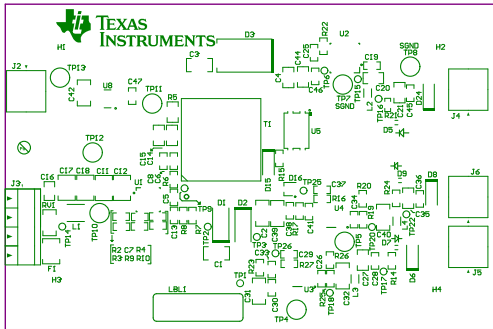


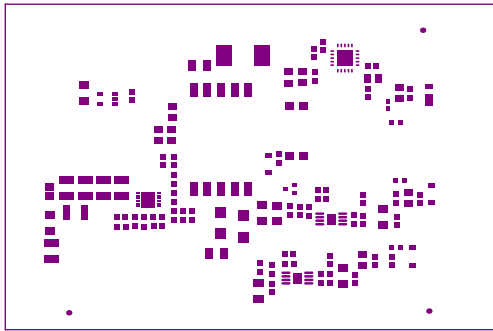
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00101	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Top Layer					
PLOT NAME =	Top Layer		GENERATED :	6/26/2015	11:47:41 AM	TEXAS INSTRUMENTS



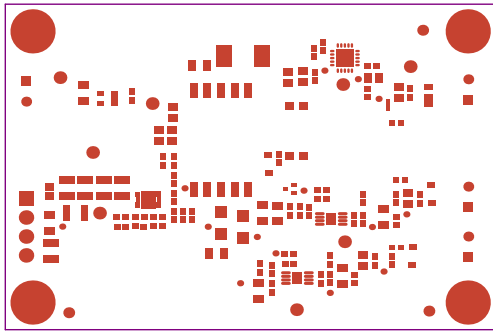
ALL PATHWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00401	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Bottom Layer					
PLOT NAME =	GENERATED :	6/26/2015	11:47:41 AM	TEXAS INSTRUMENTS		



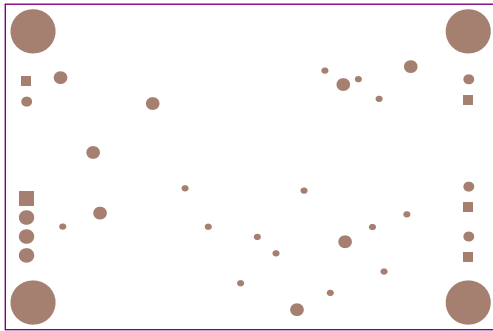
ALL PARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00101	REV: E1	SUN REV	Not In VersionControl
LAYER NAME = Top Overlay				
PLOT NAME = Top Silkscreen Overlay	GENERATED : 6/26/2015	11:47:42 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00101	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Top Paste					
PLOT NAME =	Top Paste Mask Print	GENERATED :	6/26/2015	11:47:42 AM	TEXAS INSTRUMENTS	

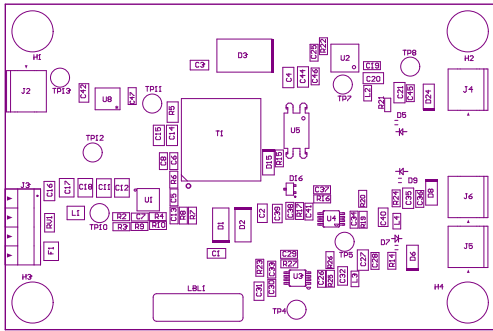


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00101	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Top Solder					
PLOT NAME =	Top Solder Mask Print	GENERATED :	6/26/2015	11:47:42 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00101	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	Bottom Solder					
PLOT NAME =	Bottom Solder Mask Print	GENERATED :	6/26/2015	11:47:42 AM	TEXAS INSTRUMENTS	

- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-D10 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOM# R: TIDA-00401	REV: E1	SUN REV	Not In VersionControl
IGNORE -> ASSEMBLY TOP				
PLOT NAME = P5 Assembly Top	GENERATED : 6/26/2015	11:47:42 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #	TIDA-00401	REV E1	SUN REV	Not In VersionControl
	IGNORE ->			ASSEMBLY BOTTOM	
PLOT NAME = H6 Assembly Bottom	GENERATED	:	6/26/2015	11:47:42 AM	TEXAS INSTRUMENTS

The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Name	Order	Copper Thickness	Dielectric Thickness
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-408
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)

90MM X 60MM

Number of Layers: 2

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 7.87 MIL

MIN. VIA PAD SIZE: 19.685 MIL

MINIMUM ANNUAL RING: 0.152mm (0.006) EXTERNAL

PER PC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL

PRECISION CONTROLLED BOARDING

MATERIAL:

FR-408 FR-4 High Tg OTHER

THICKNESS: 62.99 MIL (1.6mm) +/-10% OTHER

TOLERANCE: ANSI PC-6012 TYPE 3 CLASS 2 OTHER +/-

BOW & TWIST: ANSI PC-6012 TYPE 3 CLASS 2 OTHER +/-

DRILLING:

REFERENCE: AS SHOWN NC_DRILL FILES

PTH MIN COPPER THICKNESS: 1MIL OTHER

BOARD FINISH:

SLURSCREEN: TOP BOTTOM

SLURSCREEN COLOR: WHITE OTHER

SOLDER RESIST COLOR: GREEN BLUE OTHER

SURFACE FINISH:

IMMERSION GOLD (ENIG) ENIG

MIL TR/SILVER OR EQUIV OTHER

ARRAY/PANEL:

CUT AND TRIM PER MEDH LAYER 1 V. SCORE

NC. ROUTE

CERTIFICATION:

MATERIALS AND WORKMANSHIP FOR ALL POSIS TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI PC-A-600F CLASS -> 1 2 3

UL 94V-0 RoHS OTHER PER ORDER

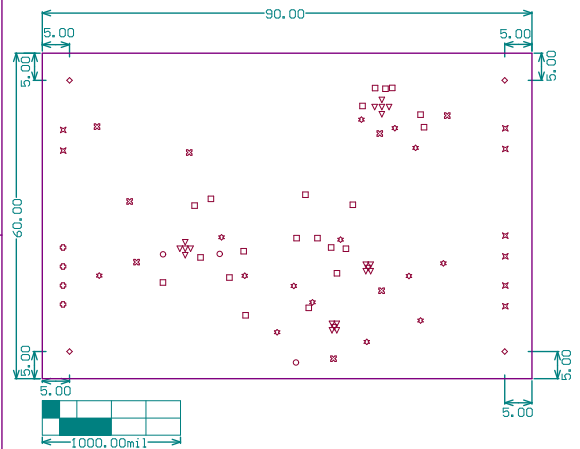
ADDITIONAL REQUIREMENTS:

MICROSECTION: YES NONE REQUIRED PER ORDER

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

MANUFACTURERS UL: RAL METAL SILK

WAS TO BE TINTED: YES



Symbol	Ht	Count	Tool Size	Plated	Hole Type
F	20	7.87mm (.310)	PTH	Round	
o	2	12mil (.305mm)	PTH	Round	
□	21	16mil (.406mm)	PTH	Round	
e	14	20mil (.508mm)	PTH	Round	
⊗	8	43.307mil (1.1mm)	PTH	Round	
○	4	50mil (1.27mm)	PTH	Round	
⊖	8	63mil (1.6mm)	PTH	Round	
+	4	125.884mil (3.2mm)	PTH	Round	
o	82	Total			

Drill Table



PROJECT TITLE: TIDA-00401

DESIGNED FOR: Public Release

FILE NAME: TIDA-00401.PcbDoc

ALL PARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00401	REV#: E1	SUN REV	Not In VersionControl
LAYER NAME = Drill Drawing				
PLOT NAME = Drill Drawing For (Bottom Layer, Top Layer)	GENERATED: 6/26/2015 11:47:42 AM	TEXAS INSTRUMENTS		

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ENGINEER: N Balakrishna	LAYOUT BY: Manjunatha T N
SCALE: 0.72	ALTIM DESIGNER VERSION: ID: 0.0.22084

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